

100V N-Channel Enhancement Mode MOSFET**Description**

The PECN4N10PR uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and high density cell Design for ultra low on-resistance. This device is suitable for use as a load switch or in PWM applications.

General Features

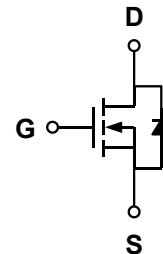
- ◆ $V_{DS} = 100V$, $I_D = 4A$
 $R_{DS(ON)}(\text{Typ.}) = 150\text{m}\Omega$ @ $V_{GS} = 10V$
 $R_{DS(ON)}(\text{Typ.}) = 160\text{m}\Omega$ @ $V_{GS} = 4.5V$
- ◆ High power and current handing capability
- ◆ Lead free product is acquired
- ◆ Surface mount package

Application

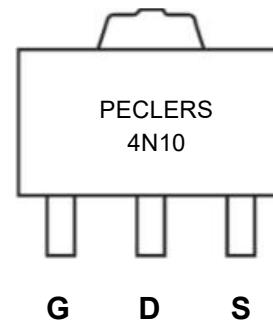
- ◆ PWM applications
- ◆ Load switch

Package

- ◆ SOT-89-3L

**Schematic diagram****Marking and pin assignment**

SOT-89-3L
(TOP VIEW)

**Ordering Information**

Part Number	Storage Temperature	Package	Devices Per Reel
PECN4N10PR	-55°C to +150°C	SOT-89	1000

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter	symbol	limit	unit
Drain-source voltage	V_{DS}	100	V
Gate-source voltage	V_{GS}	± 20	V
Drain current-continuous ^a @Tj=125°C -pulse d ^b	I_D	4	A
	I_{DM}	16	A
Drain-source Diode forward current	I_S	4	A
Maximum power dissipation	P_D	1.25	W
Operating junction Temperature range	T_j	-55—150	°C

Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	100	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =100V, V _{GS} =0V	-	-	1	μA
Gate-body leakage	I _{GSS}	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
ON Characteristics						
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1	1.6	2.5	V
Drain-source on-state resistance	R _{DS(ON)}	V _{GS} =10V, I _D =4A	-	150	165	mΩ
		V _{GS} =4.5V, I _D =4A		160	175	
Forward transconductance	g _{fs}	V _{GS} =5V, I _D =5A	1	-	-	S
Dynamic Characteristics						
Input capacitance	C _{ISS}	V _{DS} =50V, V _{GS} =0V f=1.0MHz	-	650	-	pF
Output capacitance	C _{OSS}		-	24	-	
Reverse transfer capacitance	C _{rss}		-	20	-	
Switching Characteristics						
Turn-on delay time	t _{D(ON)}	V _{DD} =50V R _L =19 ohm V _{GS} =10V R _G =3ohm	-	6	-	ns
Rise time	t _r		-	4	-	
Turn-off delay time	t _{D(OFF)}		-	20	-	
Fall time	t _f		-	4	-	
Total gate charge	Q _g	V _{DS} =50V I _D =1A V _{GS} =10V	-	20	-	nC
Gate-source charge	Q _{gs}		-	2.1	-	
Gate-drain charge	Q _{gd}		-	3	-	
DRAIN-SOURCE DIODE CHARACTERISTICS						
Diode forward voltage	V _{SD}	V _{GS} =0V, I _s =2A	-	0.76	1.16	V

Notes:

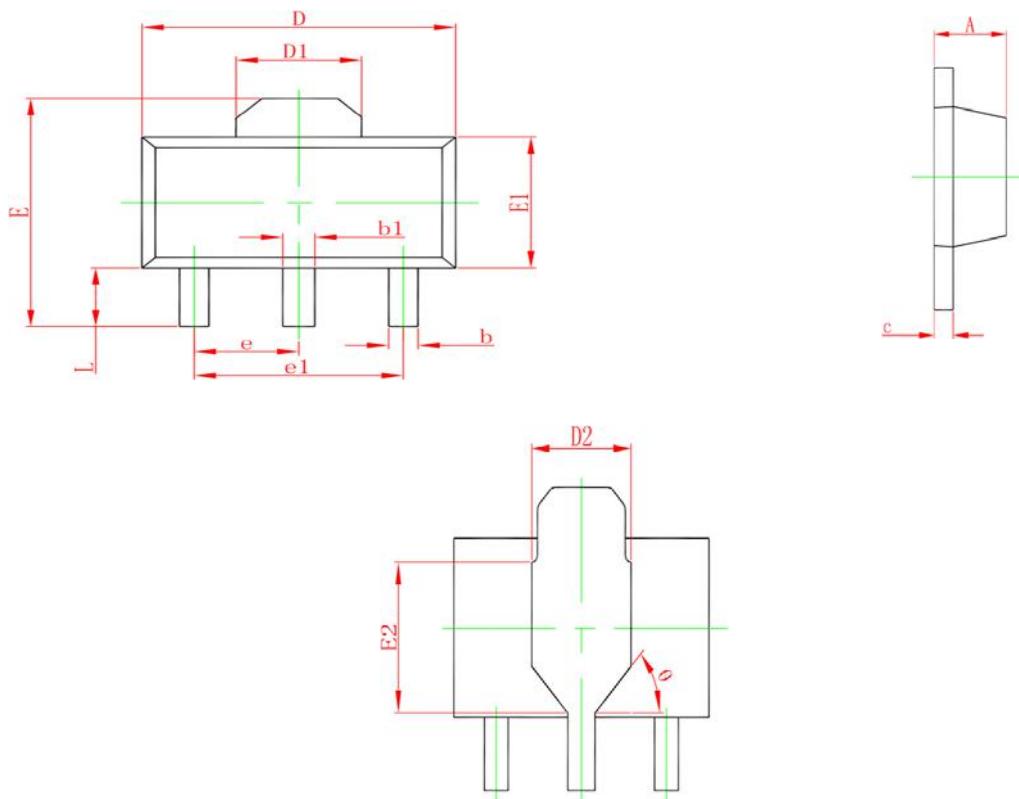
- a. surface mounted on FR4 board, t≤10sec
- b. pulse test: pulse width≤300μs, duty≤2%
- c. guaranteed by design, not subject to production testing

Thermal Characteristics

Thermal Resistance junction-to ambient	R _{θJA}	100	°C/W
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Package Information

- SOT-89-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.400	1.600	0.055	0.063
b	0.320	0.520	0.013	0.020
b1	0.380	0.580	0.015	0.023
c	0.350	0.440	0.014	0.017
D	4.400	4.600	0.173	0.181
D1	1.550 REF.		0.061 REF.	
D2	1.750 REF.		0.069 REF.	
E	3.940	4.250	0.155	0.167
E1	2.300	2.600	0.091	0.102
E2	1.900REF.		0.075REF.	
e	1.500 TYP.		0.060 TYP.	
e1	3.000 TYP.		0.118 TYP.	
L	0.900	1.200	0.035	0.047
θ	45°		45°	